What is claimed is:

- A semiconductor integrated circuit device, comprising:
 - a semiconductor substrate;
- a multilayer interconnection layer provided on said semiconductor substrate;

an integrated circuit portion provided in a surface of the semiconductor substrate and in the multilayer interconnection layer;

- a temperature monitor portion provided at a higher level than the multilayer interconnection layer, the temperature monitor portion having electric characteristics that are changed in accordance with a temperature; and
- a detector section, connected to the temperature

 15 monitor portion, operable to detect the electric

 characteristics of the temperature monitor portion to

 measure the temperature.
 - 2. The semiconductor integrated circuit device according to claim 1, wherein
- said integrated circuit portion is controlled based on an output from the detector section.
 - 3. The semiconductor integrated circuit device according to claim 1, wherein
- at least a part of the integrated circuit portion is 25 arranged directly below the temperature monitor portion.
 - 4. The semiconductor integrated circuit device according to claim 1, wherein
 - a plurality of said temperature monitor portions are

provided to detect the temperatures of a plurality of positions.

- 5. The semiconductor integrated circuit device according to claim 1, further comprising a bonding pad provided at the lower level than the temperature monitor portion.
- 6. The semiconductor integrated circuit device according to claim 1, wherein

the temperature monitor portion is formed of a

10 material having a resistance that changes in accordance with
the temperature, and the detector section detects the
resistance of the material.

- 7. The semiconductor integrated circuit device according to claim 6, wherein
- the material is a metal oxide.
 - 8. The semiconductor integrated circuit device according to claim 7, wherein

the metal oxide is vanadium oxide.

9. The semiconductor integrated circuit device 20 according to claim 6, wherein

the material is formed in a shape of sheet.